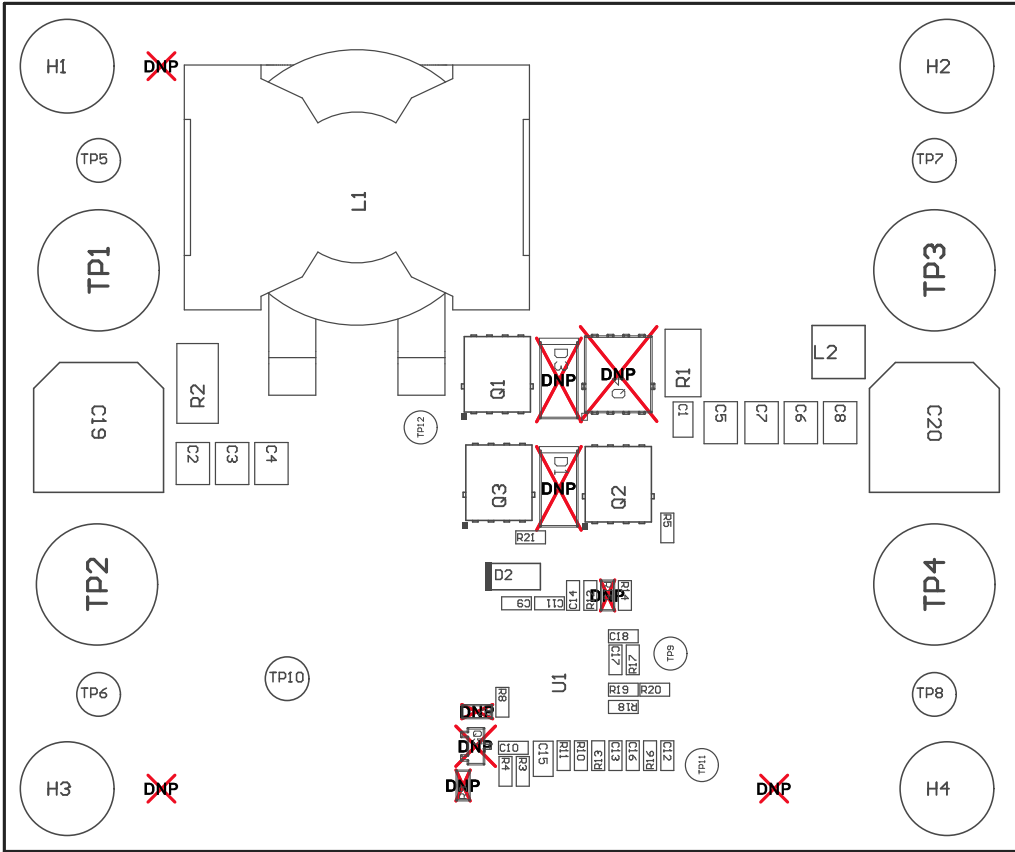
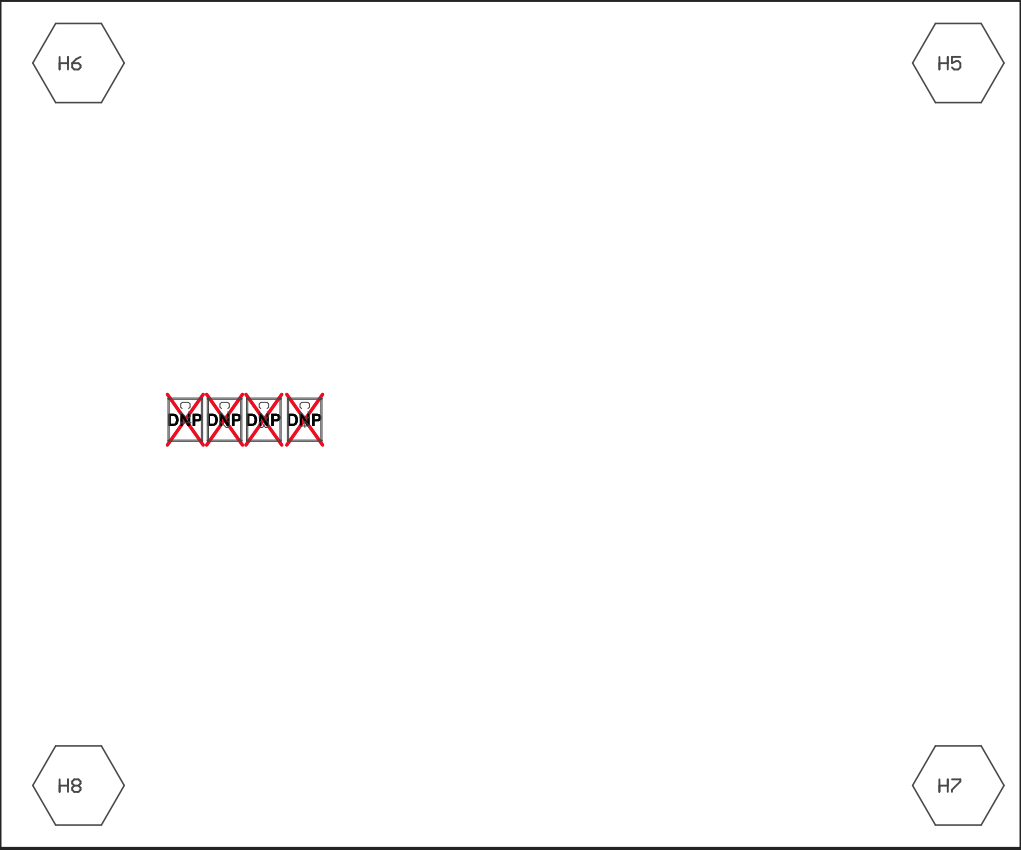


Z22 ■ This Assembly Note will show in the PcbDoc and associated outputs  
 Z23 ■ This Assembly Note will show in the PcbDoc and associated outputs  
 Z24 ■ This Assembly Note will show in the PcbDoc and associated outputs



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP21274	REV: A	SUN REV: Not In VersionControl
	TID #: PMP21274		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/29/2017 2:55:12 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP21274	REV: A	SVN REV: Not In VersionControl
	TID #: PMP21274		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/29/2017 2:55:14 PM		TEXAS INSTRUMENTS

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